

**Monday 3/10/14 10:30am**

## **A CLEAN START**

There's no doubt about it, clean contacts in contactors and sockets work a lot better than dirty ones. So what better place to start looking at burn-in and test strategies than with a close look at contamination control and cleaning processes to improve yields, test time and re-test reduction? This session begins with three hypotheses of the causes for contact contamination, Along with guidance on procedural changes for improved performance. The next presentation offers a solution to the havoc high temperature burn-in can wreak on devices under test (DUTs) with a specialized coating process to prevent solder contamination of contacts and deformation of the solder bumps on the DUT. The final two presentations examine online cleaning processes. The first focuses on a characterization tool that determines the effectiveness of online cleaning, while the second is directed at an automatic cleaning solution for a bowl fed handler used with a RF contactor. Hey, it's a dirty job, but somebody's got to do it.

This Paper

### **Contamination Mechanisms of Contact Probes**

Jon Diller, Kevin DeFord—Smiths Connectors | IDI

### **Special Coating Cleans-Up a Mess**

Paul Ruo—Aries Electronics, Inc.

Erik Orwoll—Contact Coatings, LLC

### **Unique Methodologies for Investigating On-line Cleaning Process Parameters and Recipe Optimization**

Jerry J. Broz, Ph.D., Soheil Khavandi, Bret Humphrey—International Test Solutions

### **Yield and Test Time Improvement via Automated Online Cleaning**

Brent Edington—TriQuint

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# Contamination Mechanisms of Contact Probes

**Jon Diller, Kevin DeFord**  
**Smiths Connectors | IDI**



**2014 BiTS Workshop**  
**March 9 - 12, 2014**

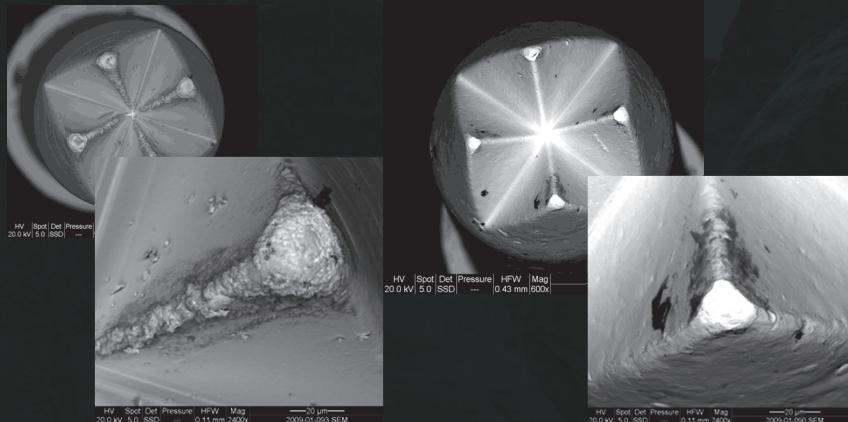
smiths connectors



## Content

- **BGA probe contamination today**
- **Why ‘how’ matters**
- **Thermal interdiffusion**
- **Voltaic transfer**
- **Fretting transfer**
- **Further work**

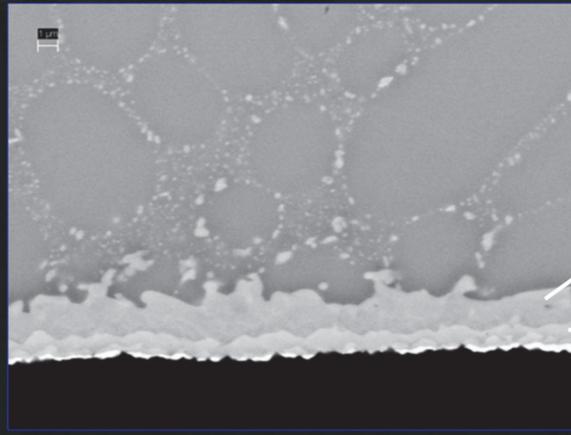
## BGA Contamination



- Organic and metallic
- Externally reducible rise in CRES

Photos from DeFord 2009

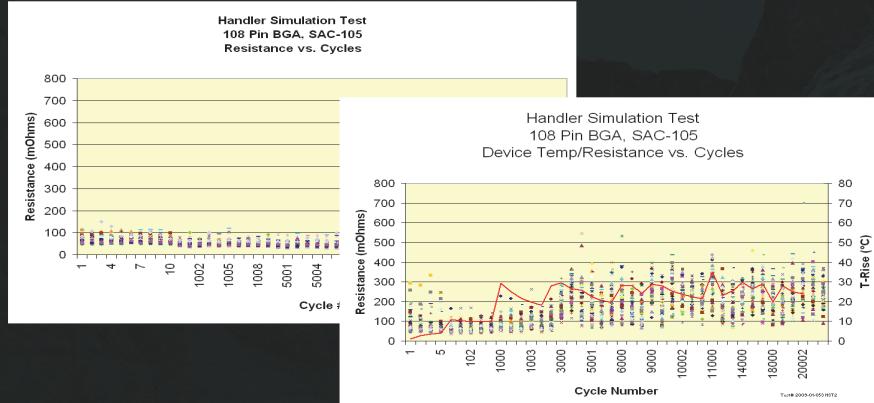
## BGA Contamination



Source: "Examination of the Formation of Au-Sn Intermetallic Compounds at Au/SnAgCu Interfaces in the Solid State", Gao, Arfei and Cotts, SUNY Binghamton, 2007.

- Langston (2008) demonstrates Sn-Au intermetallic layer

### BGA Contamination



**DeFord (2009) correlated rate of contamination with current volume and density**

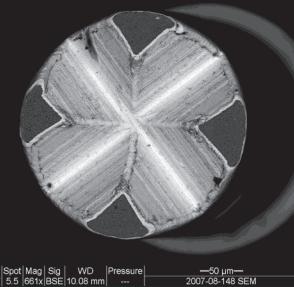
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### Why ‘How’ Matters

- Homogeneous probes make cleaning effective
- Cleaning is still ‘bad’
- Sensitivity of devices can be predicted
- Intermediary layers may be available



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Paper #1  
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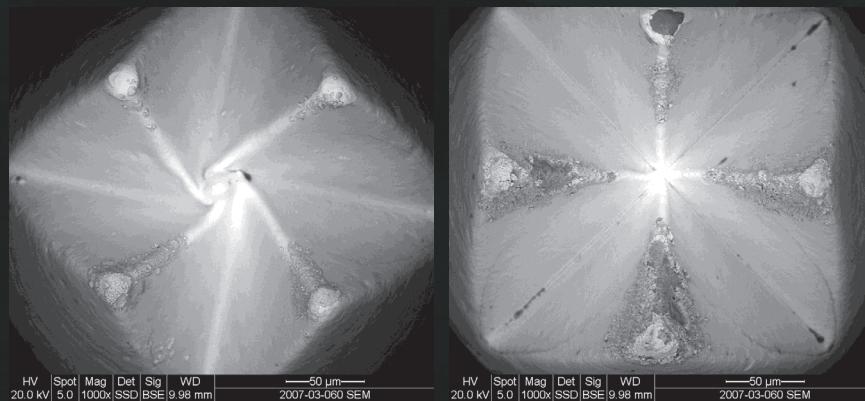
### Interdiffusion as a Function of Temperature

"The formation of intermetallic layers arises from the inter-diffusion of materials across a bimetallic interface. In electrical contacts, this interdiffusion occurs when the electrical interface is operated in a high-temperature environment or when sufficient electric current is passed through the contact to raise the temperature of the α-spot to well above the ambient temperature."

-- Timsit (2013)

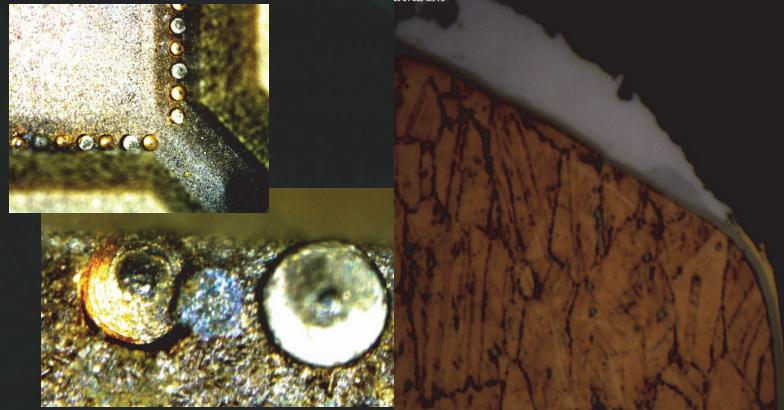


### Interdiffusion as a Function of Temperature



Before and after 24 hours at 125C SAC105

### Electromigration



- DeFord (2009) demonstrates cathodic – anodic behavior in series with diffusion

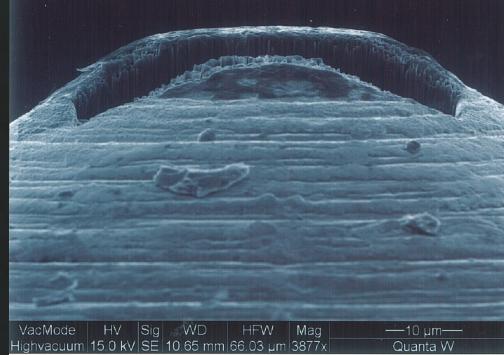
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### Fretting Transfer

- Some contamination has no diffusion



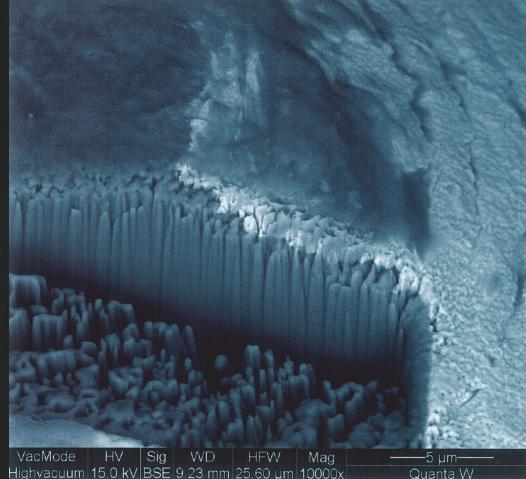
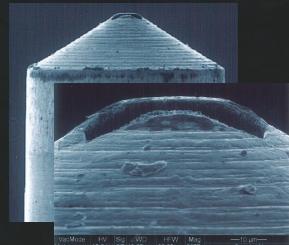
VacMode | HV | Sig | WD | HFW | Mag | —10 µm—  
Highvacuum | 15.0 kV | SE | 10.65 mm | 66.03 µm | 3877x | Quanta W

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## Fretting Transfer



- Timsit (2013) describes fretting transfer
- Lubricant affects contamination

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## Summary

Mechanism	Inter-diffusion?	Lubricant?	Hardness?	Smoothness?	Force?
Thermal	Yes	No	Negative	Positive	Positive
Galvanic	Maybe	Maybe	Negative	Neutral	Positive
Fretting	No	Yes	Positive	Positive	Positive

- All rely on differing metals
- Suggests further evaluation of:
  - Lubricants
  - Smoothness

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## Acknowledgements

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- Khaled Elmabdouly
- Rick Westpfahl
- Frank Zhou

## References

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